



Bill of Materials

TI DESIGNS

TIDM-RF430-TEMPSENSE

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	1	Antenna Coil						PCBComponent_1	
2	2	C1, C5	22pF	Capacitor (Semiconductor SIM Model)				0402	
3	1	C2	DNP	Capacitor (Semiconductor SIM Model)				0402	
4	5	C3, C4, C8, C9, C12	0.1uF	Capacitor (Semiconductor SIM Model)				0402	
5	1	C6	2.2uF	Capacitor (Semiconductor SIM Model)				0402	
6	1	C7	0.01uF	Capacitor (Semiconductor SIM Model)				0402	
7	1	C10	43pF	Capacitor (Semiconductor SIM Model)				0402	
8	1	C11	1uF	Capacitor (Semiconductor SIM Model)				0402	
9	2	R1, R2	1.00k	RES, 1.00 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04021K00FKED		0402	
10	1	R3	100k	RES, 100 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402100KJNED		0402	
11	1	R4	10k	RES, 10 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW040210K0JNED		0402	
12	1	RT1	100k ohm	Thermistor NTC, 10.0k ohm, 1%, Disc, 5x8.4 mm	SEMITEC Corporation	103AT-2		0603	
13	1	U1		Sensor Transponder		RF430FRL152HCRGER		RGE24_2P7X2P7	

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